



Torex...Powerfully Small!

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9265xxxx4R-G

Typical Mass: 4 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.466 | Silicon | 116600 | 7440-21-3 |
| | | - Arsenic | <1 | 7440-38-2 |
| Lead pad | 1.220 | Nickel | 305000 | 7440-02-0 |
| | | Silver | 14000 | 7440-22-4 |
| | | Gold | 3000 | 7440-57-5 |
| Die attach | 0.025 | Epoxy Resin | 6300 | — |
| | | Aluminum oxide | 5300 | 1344-28-1 |
| | | Silica | 100 | — |
| Bonding wire | 0.083 | Gold | 20700 | 7440-57-5 |
| Resin | 1.852 | Silica | 463000 | 60676-86-0 |
| | | Epoxy Resin | 26400 | — |
| | | Phenol Resin | 23800 | — |
| | | Metal hydroxide | 15900 | — |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."